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Supporting Information

Fabrication of flexible copper pattern based on sub-micro copper paste by low temperature plasma technique

Yue Gao, Hao Zhang, Jinting Jiu*, Shijo Nagao, Tohru Sugahara, Katsuaki Suganuma
The Institute of Scientific and Industrial Research (ISIR), Osaka University, Osaka, Japan

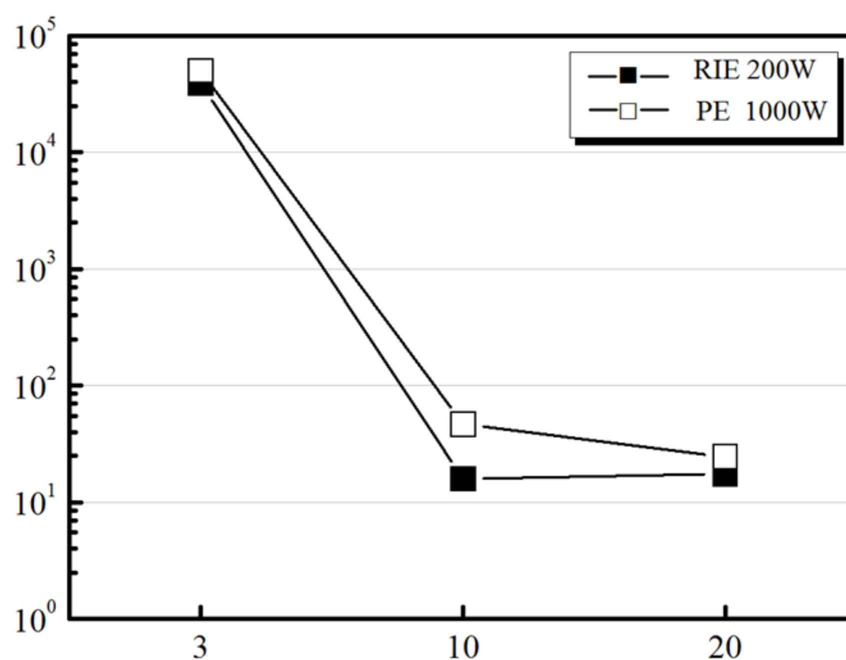

Fig. S1. Electrical resistivity of Cu patterns with PE and RIE models.

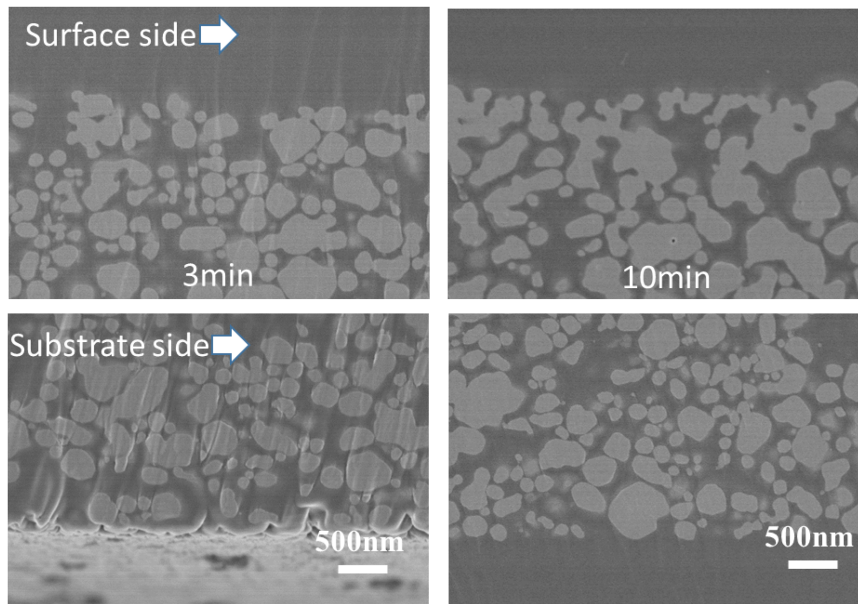

Fig.S2 Cross-section of copper patterns with PE model at 1000W

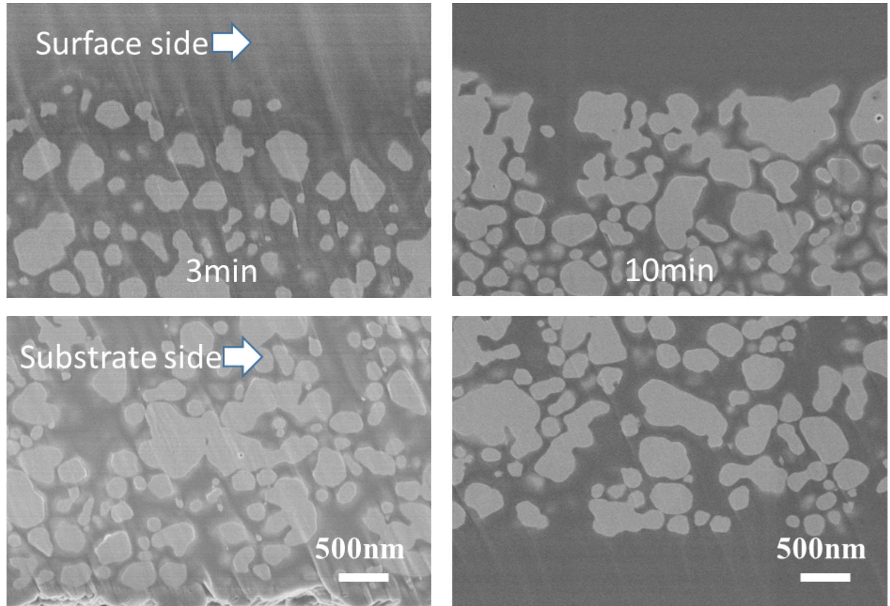

Fig.S3 Cross-section of copper patterns with RIE model at 200W.

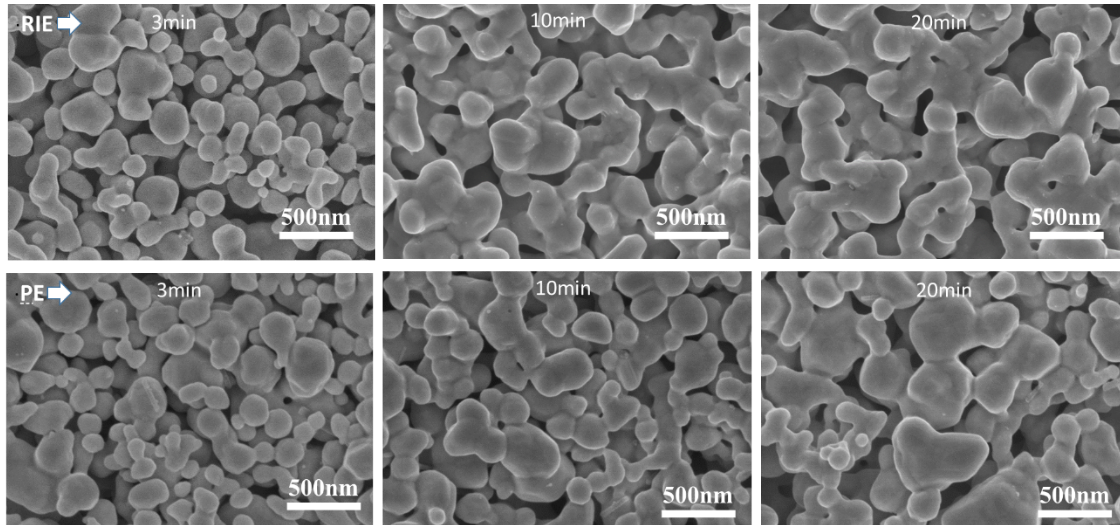

Fig. S4. SEM surface images of Cu patterns sintered with RIE and PE model at 200 W and 1000W, respectively.

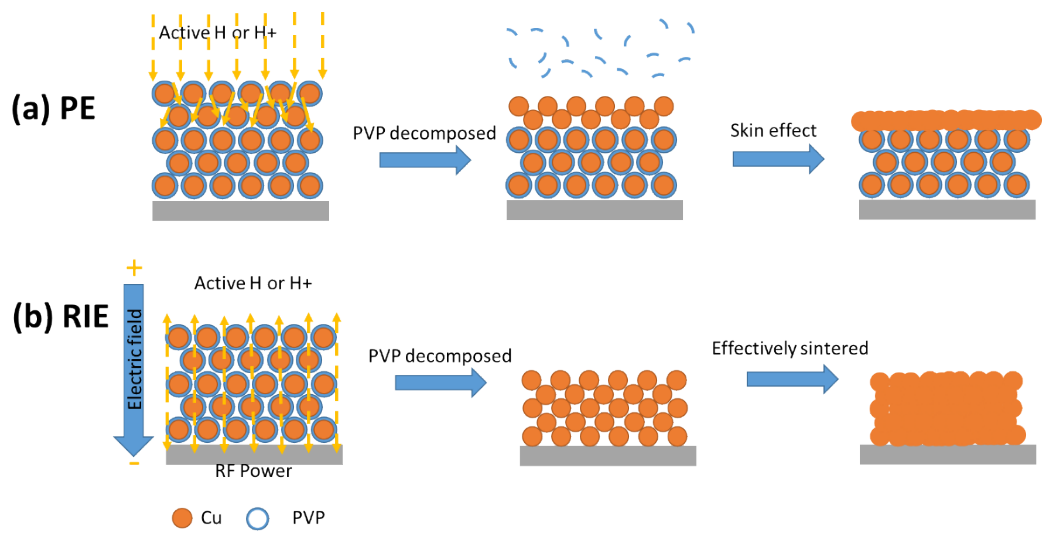

Fig.S5 Schematic diagram of the mechanism of PE mode (a) and RIE mode (b).